

	Type	Hits	Search Text	DBs	Time Stamp
1	BRS	26	semiconductor adj chip and package and "heat slug"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/03/26 12:19
2	BRS	90	chip and package and "heat slug"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/03/23 13:21
3	BRS	64	chip and package and "heat slug" not (semiconductor adj chip and package and "heat slug")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/03/23 14:13
4	BRS	201	chip and package and slug not (chip and package and "heat slug")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/03/23 16:04
5	BRS	9085	chip and package and plate not (chip and package and slug not (chip and package and "heat slug"))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/03/23 16:04
6	BRS	205	chip and package and cold adj plate not (chip and package and slug not (chip and package and "heat slug"))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/03/23 16:32
7	BRS	119	257/720.icls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/03/23 17:17
8	BRS	1	(257/678.icls.) and "heat slug"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/03/23 17:19
9	BRS	5	(257/678.icls.) and "slug"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/03/23 17:19
10	BRS	5	(257/678.icls.) and slug	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/03/23 17:22
11	BRS	3	(257/678.icls.) and "cold plate"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/03/23 17:25
12	BRS	110	(257/678.icls.) and plate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/03/23 17:25

	Type	Hits	Search Text	DBs	Time Stamp
13	BRS	3	5726079.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/03/26 13:10
14	BRS	1	"5405809".PN.	USPAT	2001/03/26 12:19
15	BRS	1	"5471027".PN.	USPAT	2001/03/26 12:22
16	BRS	1	"5471027".PN.	USPAT	2001/03/26 12:22
17	BRS	1	"5359768".PN.	USPAT	2001/03/26 12:22
18	BRS	1	"5222014".PN.	USPAT	2001/03/26 12:24
19	BRS	1	"4959900".PN.	USPAT	2001/03/26 12:24
20	BRS	1	"4941255".PN.	USPAT	2001/03/26 12:24
21	BRS	1	"4794981".PN.	USPAT	2001/03/26 12:25
22	BRS	1	"4654966".PN.	USPAT	2001/03/26 12:25
23	BRS	1	"4571826".PN.	USPAT	2001/03/26 12:25
24	BRS	1	"3570115".PN.	USPAT	2001/03/26 12:25
25	BRS	1	"4023198".PN.	USPAT	2001/03/26 12:25
26	BRS	1	"4571826".PN.	USPAT	2001/03/26 12:26
27	BRS	1	"4654966".PN.	USPAT	2001/03/26 12:26
28	BRS	1	"5289346".PN.	USPAT	2001/03/26 12:27
29	BRS	25	(257/706.icls.) and heat adj slug	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/03/26 13:16

	Type	Hits	Search Text	DBs	Time Stamp
30	BRS	0	(257/70.icls.) and heat adj slug	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/03/26 13:17
31	BRS	15	(257/707.icls.) and heat adj slug	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/03/26 13:18
32	BRS	6	(257/778.icls.) and heat adj slug	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/03/26 13:20
33	BRS	4	(257/722.icls.) and heat adj slug	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/03/26 13:26
34	BRS	1	"5289346".PN.	USPAT	2001/03/26 13:21
35	BRS	1	"5359768".PN.	USPAT	2001/03/26 13:21
36	BRS	1	"5405809".PN.	USPAT	2001/03/26 13:22
37	BRS	1	"5410451".PN.	USPAT	2001/03/26 13:22
38	BRS	6	(438/122.icls.) and heat adj slug	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/03/26 14:48
39	BRS	1	(257/706.icls.) and heat adj slug and solder adj film	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/03/26 15:00
40	BRS	0	(257.icls.) and heat adj slug and solder adj film	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/03/26 15:01
41	BRS	2	heat adj slug and solder adj film	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/03/26 15:04
42	BRS	6	slug and solder adj film	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/03/26 16:28

	Type	Hits	Search Text	DBs	Time Stamp
43	BRS	12	slug and solder adj layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/03/26 16:32
44	BRS	1462	plate and solder adj layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/03/26 16:33
45	BRS	225	plate and solder adj layer and metal adj layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/03/26 16:34
46	BRS	0	heat adj plate and solder adj layer and metal adj layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/03/26 16:34
47	BRS	103	plate and solder adj layer and metal adj layer and chip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/03/26 16:35
48	BRS	88	plate and solder adj layer and metal adj layer and chip and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/03/26 16:35
49	BRS	37	plate and solder adj layer and metal adj layer and chip and substrate and bump	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/03/26 18:13
50	BRS	1	cold adj plate and solder adj layer and metal adj layer and chip and substrate and bump	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/03/26 16:46
51	BRS	2	4926242.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/03/26 18:13

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USPT	5683937.pn. or 5811317.pn. or 5336364.pn. or 6060778.pn.	4	<u>L16</u>
USPT	Heat adj sink and chip and substrate and adhesive adj layer and material and elastomer	44	<u>L15</u>
USPT	Heat adj sink and chip and substrate and adhesive adj layer and elastomer	44	<u>L14</u>
USPT	Heat adj sink and chip and substrate and adhesive adj layer and elastomer	44	<u>L13</u>
USPT	Heat adj sink and chip and substrate and anodizing adj layer	2	<u>L12</u>
USPT	(Heat adj sink and (cupper)) and chip and substrate	3	<u>L11</u>
USPT	(Heat adj sink and (cupper or "Al")) and chip and substrate	3491	<u>L10</u>
USPT	Heat adj sink and chip and substrate and underfilling adj material	1	<u>L9</u>
USPT	Heat adj sink and chip and substrate and underfilling adj material	1	<u>L8</u>
USPT	Heat adj sink and adhesion and material and "Ti/Pt/Au"	14	<u>L7</u>
USPT	Heat adj sink and adhesion and material	1967	<u>L6</u>
USPT	6088915.pn. and heat adj sink and (silicon adj rubber or elastomer)	1	<u>L5</u>
USPT	5359768.pn. and heat adj sink and (silicon adj rubber or elastomer)	0	<u>L4</u>
USPT	5359768.pn. and heat adj sink and Al	1	<u>L3</u>
USPT	5359768.pn. and heat adj sink and cupper	0	<u>L2</u>
USPT	5359768.pn. and heat adj sink and cupper or Al	2226085	<u>L1</u>